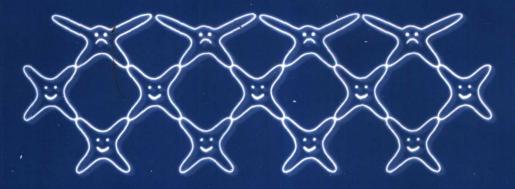
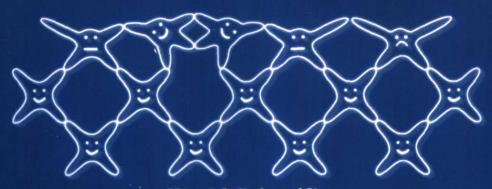
Silicon Surfaces and Formation of Interfaces

硅表面及界面的形成 J.Dabrowski,H-J.Müssig





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Basic Science in the Industrial World

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Basic Science in the Industrial World

To my Parents, and to Ewa and Wojtek, for their understanding, patience, and love.

Moim Rodzicom oraz Ewie i Wojtkowi, za ich zrozumienie, cierpliwość i miłość.

- J. D.

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Preface

Silicon is the material of choice of the multibillion semiconductor industry. Ongoing miniaturization of microelectronic devices drives critical regions of integrated circuits ever closer to the place where the silicon ends and another material begins, to the interfacial region. Performance and reliability of electronic microelements depend more and more on the microscopic quality of the interfaces and on the microscopic-scale quality of the original Si surfaces. Suffice to say that as soon as in the first decade of the coming millenium the customers will be offered microelectronic chips with minimum features about hundred atoms long and a couple of atoms thick! Small wonder that atomic-scale knowledge is gaining a commercial value.

Determination of the atomic structure and the chemical bonding at semiconductor surfaces and interfaces is a demanding task. Advances in the experimental and computational techniques make this task increasingly managable. The work of physicists is assisted by dramatic improvements in the performance of computers. Fruitful interaction between predictable theories and reliable experiments has greatly influenced our knowledge on the intricated relationship between the behavior of individual atoms and the behavior of mesoscopic and macroscopic objects. We are approaching the ultimate practical goal of modern semiconductor surface research: efficient usage of microscopic information in the control of semiconductor structure and chemistry and, consequently, efficient control of technological processes and design of optimal circuits and systems.

The main objective of this book is to give a comprehensive overview of silicon surfaces and interfaces: what is known and unknown about them from scientific point of view, what is their industrial role, what are the viii Preface

relations between applications and basic research, what are the most probable directions of future developments. Since the scope is broad and the volume small, I took care to avoid the danger that this presentation evolves into an unreadable encyclopaedia accessible only to experts. In fact, there is no particular reason to compile all the data; first, this has been done many times before, and second, this would be a task for a large team. So I decided to focus not on numbers and curves, but on problems. A reader interested in more details is often asked to consult an easily available book or a journal article.

Each technical chapter begins with a general overview, intended to be understandable to any person with some basic knowledge on solid state physics. Individual Sections begin with overviews as well, but these have a more specialized character. Subsections deal with their subjects much more thoroughly and they do not avoid controversial or speculative issues. We have used the advantage of the storyteller and limited the scope of material covered in detail to the topics we found either most interesting or of a major practical importance.

Practical importance is likely to invoke scientific interest. But many subjects which are scientifically interesting have no technological relevance. When combined with lame budgets of many governments, an unfortunate but far-reaching consequence of this trivial fact may be that science will be commercialized. Let us hope that scientists will eventually contain this danger by recognizing the problem, by some self-control, and by occasional refreshing exercises in broader, even philosophically oriented thinking.

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Jarek Dąbrowski Frankfurt (Oder), 9 May 1999

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